

Title (en)

METHOD FOR MANUFACTURING A MICROFLUIDIC DEVICE AND DEVICE MANUFACTURED USING SAID METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER MIKROFLUIDISCHEN VORRICHTUNG UND MIT DIESEM VERFAHREN ERHALTENE VORRICHTUNG

Title (fr)

PROCÉDÉ DE FABRICATION D'UN DISPOSITIF MICRO-FLUIDIQUE ET DISPOSITIF FABRIQUÉ PAR LEDIT PROCÉDÉ

Publication

**EP 3971133 B1 20230322 (FR)**

Application

**EP 21196249 A 20210913**

Priority

FR 2009399 A 20200917

Abstract (en)

[origin: US2022080412A1] A process for manufacturing a micro-fluidic device, the device including a substrate made of thermoplastic polymer having a face called the upper face and a first micro-fluidic circuit that includes at least one aperture that opens onto the upper face, and a component bearing pads arranged to become anchored in the substrate on the periphery of the aperture, the process including the following steps: heating so that the anchoring pads of the component reach a temperature at least equal to the glass-transition temperature of the substrate; fastening the component to the substrate by embedding then anchoring its pads in the substrate.

IPC 8 full level

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CPC (source: EP US)

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